



625kSPS, 24-Bit Analog-to-Digital Converter

Check for Samples: ADS1672

FEATURES

- AC Performance: 107dB of Dynamic Range at 625kSPS 115.5dB of Dynamic Range at 78kSPS –113dB THD
- DC Accuracy: 3ppm INL 2μV/°C Offset Drift 2ppm/°C Gain Drift
- Programmable Digital Filter with User-Selectable Path:
 - Low-Latency: Completely settles in 5.5µs
 - Wide-Bandwidth: 305kHz BW with flat passband
- Flexible Read-Only Serial Interface:
 - Standard CMOS
 - Serialized LVDS
- Easy Conversion Control with START Pin
- Out-of-Range Detection
- Supply: Analog +5V, Digital +3V
- Power: 350mW

APPLICATIONS

- Automated Test Equipment
- Vibration Analysis
- Sonar
- Test and Measurement

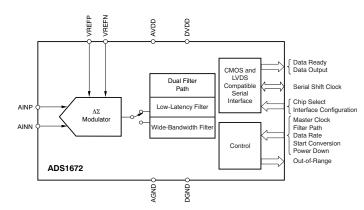
DESCRIPTION

The ADS1672 is a high-speed, high-precision analog-to-digital converter (ADC). Using an advanced delta-sigma ($\Delta\Sigma$) architecture, it operates at speeds up to 625kSPS with outstanding ac performance and dc accuracy.

The ADS1672 ADC is comprised of a low-drift, chopper-stabilized modulator with out-of-range detection and a dual-path programmable digital filter. The dual filter path allows the user to select between two post-processing filters: low-latency or wide-bandwidth. The low-latency filter settles quickly in one cycle, for applications with large instantaneous changes, such as a multiplexer. The wide-bandwidth path provides an optimized frequency response for ac measurements with a passband ripple of less than 0.001dB, stop band attenuation of 86dB, and a bandwidth of 305kHz.

The ADS1672 is controlled through I/O pins—there are no registers to program. A dedicated START pin allows for direct control of conversions: toggle the START pin to begin a conversion, and then retrieve the output data. The flexible serial interface supports data readback with either standard CMOS and LVDS logic levels, allowing the ADS1672 to directly connect to a wide range of microcontrollers, digital signal processors (DSPs), or field-programmable grid arrays (FPGAs).

The ADS1672 operates from an analog supply of 5V and digital supply of 3V, and dissipates 350mW of power. When not in use, the PDWN pin can be used to power down all device circuitry. The device is fully specified over the industrial temperature range and is offered in a TQFP-64 package.



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

For the most current package and ordering information, see the Package Option Addendum at the end of this datasheet or see the TI website at www.ti.com.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Over operating free-air temperature range (unless otherwise noted).

	PARAMETER	ADS1672	UNIT
AVDD to A	AGND	-0.3 to +6	V
DVDD to I	DGND	-0.3 to +3.6	V
AGND to	DGND	-0.3 to +0.3	V
Input Momentary		100	mA
current Continuous		10	mA
Analog I/O to AGND		-0.3 to AVDD +0.3	V
Digital I/O	to DGND	-0.3 to DVDD +0.3	V
Maximum junction temperature		+150	°C
Operating temperature range		-40 to +85	°C
Storage te	emperature range	-60 to +150	°C

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.



ELECTRICAL CHARACTERISTICS

All specifications are at $T_A = -40^{\circ}$ C to +85°C, AVDD = 5V, DVDD = 3V, $f_{CLK} = 20$ MHz, $V_{REF} = +3V$, and $R_{BIAS} = 7.5$ k Ω , unless otherwise noted.

			ADS1672		_	
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
ANALOG INPUTS		[-			
Full-scale input voltage	$V_{IN} = (AINP - AINN)$		±V _{REF}		V	
Common-mode input voltage	$V_{CM} = (AINP + AINN)/2$		2.5		V	
AC PERFORMANCE		[1	
Data rate (f _{DATA})			See Table 2	1	kSPS	
	Inputs shorted together, wide-bandwidth path, f _{DATA} = 625kSPS	105	107			
Dynamic range	Inputs shorted together, wide-bandwidth path, f _{DATA} = 78.125kSPS	113	115.5		dB	
	$f_{\text{IN}} = 10 \text{kHz}, -0.5 \text{dBFS}, \\ \text{wide-bandwidth path}, f_{\text{DATA}} = 625 \text{kSPS}$		102			
Signal-to-noise ratio (SNR)	$f_{IN} = 10 kHz$, -2dBFS, wide-bandwidth path, $f_{DATA} = 625 kSPS$		103		dB	
	$f_{IN} = 10kHz$, –6dBFS, wide-bandwidth path, $f_{DATA} = 625kSPS$		99			
	$f_{IN} = 10 \text{kHz}, -0.5 \text{dBFS}$		-105		4	
Total harmonic distortion (THD)	$f_{IN} = 10 kHz, -2 dBFS$		-109		dB	
	$f_{IN} = 10 kHz, -6 dBFS$		-113			
Spurious-free dynamic range (SFDR)	f _{IN} = 10kHz, -0.5dBFS, signal harmonics excluded		-120		dB	
DC PRECISION	1		a. <u> </u>			
Resolution		24			Bits	
Differential nonlinearity			24-bit (monotonic)			
Integral nonlinearity	Input range of ± 0.5 dBFS, T _A = ± 25 °C		3	9.5	ppm of FS	
Offset error		-2		2	mV	
Offset error drift			2		μV/°C	
Gain error	T _A = +25°C		1	2	%	
Gain error drift			2		ppm/°C	
Noise		See	e Noise Performa	nce table (Table	2)	
Common-mode rejection	At dc		92		dB	
Power-supply rejection	At dc, AVDD		92		dB	
DIGITAL FILTER CHARACTERISTICS (WIDE-BAND	OWIDTH PATH)					
Passband		0		0.424f _{DATA}	Hz	
Passband ripple				±0.0001	dB	
Passband transition	-0.1dB attenuation		0.432f _{DATA}		Hz	
	-3.0dB attentuation		0.488f _{DATA}		Hz	
Stop band		0.576f _{DATA}		f _{CLK} – 0.576f _{DATA}	Hz	
Stop band attenuation			86		dB	
Group delay			28		t _{DRDY}	
Settling time		See Wid	le Bandwidth Filte	er section		
DIGITAL FILTER CHARACTERISTICS (LOW-LATE	NCY РАТН)					
Bandwidth	-3dB attenuation	See L	ow-Latency Filter	section		
Settling time	Complete settling		1		t _{DRDY}	
VOLTAGE REFERENCE INPUTS						
Reference input voltage (V _{REF})	V _{REF} = (VREFP – VREFN)	2.75	3.0	3.25	V	
VREFP		2.75	3.0	3.25	V	
VREFN			Short to AGND		V	

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ELECTRICAL CHARACTERISTICS (continued)

All specifications are at $T_A = -40^{\circ}$ C to +85°C, AVDD = 5V, DVDD = 3V, $f_{CLK} = 20$ MHz, $V_{REF} = +3V$, and $R_{BIAS} = 7.5$ k Ω , unless otherwise noted.

			ADS1672		
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
CLOCK (CLK)					
VIH		0.7AVDD		AVDD	V
V _{IL}		AGND		0.3AVDD	V
DIGITAL INPUTS					
V _{IH}		0.7DVDD		DVDD	V
V _{IL}		DGND		0.3DVDD	V
Input leakage	DGND < V _{IN} < DVDD			±10	μA
CMOS OUTPUTS					
V _{OH}	I _{OH} = 2mA	0.8DVDD			V
V _{OL}	I _{OL} = 2mA			0.2DVDD	V
LVDS OUTPUTS					
V _{OD(SS)}	Steady-state differential output voltage magnitude		340		mV
$\Delta V_{OD(SS)} $	Change in steady-state differential output voltage magnitude between logic states		±50		mV
V _{OC(SS)}	Steady-state common-mode voltage output		1.2		V
$\Delta V_{OC(SS)} $	Change in steady-state common-mode output voltage between logic states		±50		mV
V _{OC(pp)}	Peak-to-peak change in common-mode output voltage		50	150	mV
Short-circuit output current (I _{OS})	V_{OY} or $V_{OZ} = 0V$		3		mA
Short-circuit output current (I _{OS})	$V_{OD} = 0V$		3		mA
High-impedance output current (I _{OZ})	$V_0 = 0V \text{ or } + DVDD$		±5		μA
Load				5	pF
POWER-SUPPLY REQUIREMENTS					
AVDD		4.75	5.0	5.25	V
DVDD		2.7	3.0	3.3	V
AVDD current			51	55	mA
	CMOS outputs, DVDD = 3V		28	32	mA
DVDD current	LVDS outputs, DVDD = 3V		33	37	mA
Power dissipation	CMOS outputs, AVDD = 5V, DVDD = 3V		350	370	mW
	Power down		5		mW

TEXAS INSTRUMENTS

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TQFP PACKAGE (TOP VIEW) VREFP VREFP VREFN VREFN DGND DGND CAP2 AGND AGND AGND DVDD DVDD AVDD AVDD CAP1 CLK 64 63 62 61 60 59 58 57 56 55 54 53 52 51 50 49 48 DVDD AVDD 47 DGND AGND 2 46 DRDY AGND 3 AINN 45 DRDY 4 44 DOUT AINP 5 43 DOUT AGND 6 42 AVDD 7 SCLK RBIAS 8 41 SCLK ADS1672 40 AGND 9 RSV3 39 OTRD AGND 10 38 AVDD 11 cs 12 37 START AVDD 36 DRATE[0] VCM 13 35 DRATE[1] 14 DGND 34 DVDD DGND 15 33 FPATH DGND 16 25 26 27 28 29 30 31 32 17 18 19 20 21 22 23 24 SCLK_SEL DGND DGND DGND DGND RSV2 RSV1 DVDD DGND DGND DVDD PDWN LVDS DGND LL_CONFIG

DEVICE INFORMATION

Table 1. TERMINA	L FUNCTIONS
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PIN			
NAME	NO.	FUNCTION	DESCRIPTION
AVDD	1, 7, 11, 12, 53, 58	Analog	Analog supply
AGND	2, 3, 6, 9, 10, 54, 56, 57	Analog	Analog ground
AINN	4	Analog Input	Negative analog input
AINP	5	Analog Input	Positive analog input
RBIAS	8	Analog	Analog bias setting resistor
VCM	13	Analog	Terminal for external bypass capacitor connection to internal common-mode voltage
DGND	14, 15, 16, 17, 18, 19, 20, 25, 26, 31, 47, 50, 51	Digital	Digital ground
RSV2	21	Reserved	Short to digital ground
RSV1	22	Reserved	Short to digital ground
DVDD	23, 24, 27, 34, 48, 49, 52	Digital	Digital supply
PDWN	28	Digital Input	Power-down control, active low
SCLK_SEL	29	Digital Input	Shift-clock source select. If SCLK_SEL = '0', then SCLK is internally generated. If SCLK_SEL = '1', then SCLK must be externally generated.
LVDS	30	Digital Input	Serial interface select. If $\overline{\text{LVDS}}$ = '0', then interface is LVDS-compatible. If $\overline{\text{LVDS}}$ = '1', then interface is CMOS-compatible.

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PIN				
NAME	NO.	FUNCTION	DESCRIPTION	
LL_CONFIG	32	Digital Input	Configure low-latency digital filter. If LL_CONFIG = '0', then single-cycle settling is selected. If LL_CONFIG = '1', then fast-response is selected.	
FPATH	33	Digital Input	Digital filter path selection. If FPATH = '0', then path is wide-bandwidth. If FPATH = '1', then path is low-latency.	
DRATE[1:0]	35, 36	Digital Input	Data rate selection	
START	37	Digital Input	Start convert, reset, and synchronization control input	
CS	38	Digital Input	Chip select; active low.	
OTRD	39	Digital Output	Digital filter out-of-range indicator	
RSV3	40	Reserved	This pin must be left floating. Do not connect or short to ground.	
SCLK	41	Digital Output	Negative shift clock outp <u>ut.</u> If SCLK_SEL = '0', then <u>SCLK</u> is the complementary shift clock output. If SCLK_SEL = '1', then SCLK always output is 3-state.	
SCLK	42	Digital Input/Output	Positive shift clock output. If SCLK_SEL = '0', then SCLK is an output. If SCLK_SEL = '1', then SCLK is an input.	
DOUT	43	Digital Output	Negative LVDS serial data output	
DOUT	44	Digital Output	Positive LVDS serial data output	
DRDY	45	Digital Output	Negative data ready output	
DRDY	46	Digital Output	Positive data ready output	
CLK	55	Digital Input	Master clock input	
CAP1	59	Analog	Terminal for 1µF external bypass capacitor	
VREFN	60, 61	Analog	Negative reference voltage. Short to analog ground.	
CAP2	62	Analog	Terminal for 1µF external bypass capacitor	
VREFP	63, 64	Analog	Positive reference voltage	

Table 1. TERMINAL FUNCTIONS (continued)



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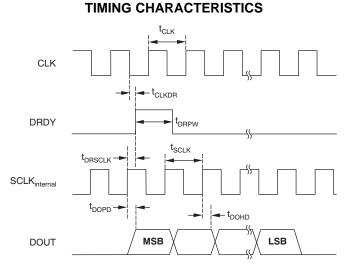


Figure 1. Data Retrieval Timing with Internal SCLK (SCLK_SEL = 0)

TIMING REQUIREMENTS: Internal SCLK

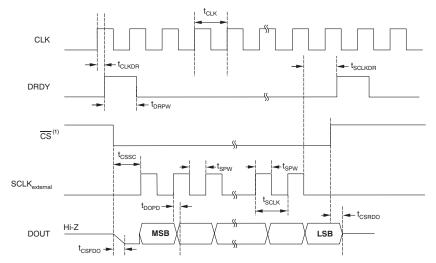
At $T_A = -40^{\circ}$ C to +85°C, and DVDD = 2.7V to 3.3V.

SYMBOL	DESCRIPTION MIN TYP M		MAX	UNIT	
t _{CLK}	CLK period (1/f _{CLK})	50			ns
t _{CLKDR}	CLK to DRDY delay		36		ns
t _{DRPW}	DRDY pulse width	1			t _{CLK}
t _{DRSCLK}	Internally-generated SCLK rising edge to DRDY rising edge	4		ns	
t _{SCLK}	SCLK period (1/f _{SCLK})	1			t _{CLK}
t _{DOPD}	Rising edge of SCLK to new valid data output (propagation delay)	3		3	ns
t _{DC}	CLK duty cycle	45 55		%	
t _{SPWH}	SCLK pulse width high	20			ns

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(1) $\overline{\text{CS}}$ may be tied low.

Figure 2. Data Retrieval Timing with External SCLK (SCLK_SEL = 1)

TIMING REQUIREMENTS: External SCLK

At $T_A = -40^{\circ}$ C to +85°C, and DVDD = 2.7V to 3.3V.

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNIT
t _{CLK}	CLK period (1/f _{CLK})	50			ns
t _{CLKDR}	CLK to DRDY delay		37		ns
t _{DRPW}	DRDY pulse width		1		t _{CLK}
t _{CSSC}	CS active low to first Shift Clock (setup time)	5			ns
t _{SCLK}	SCLK period (1/f _{SCLK})	25			ns
t _{SPW}	SCLK high or low pulse width	12			ns
t _{DOPD}	Rising edge of SCLK to new valid data output (propagation delay)			11	ns
t _{SCLKDR}	Setup time of DRDY rising after SCLK falling edge	3			t _{CLK}
t _{CRSDO}	CS inactive to data output 3-state		8		ns

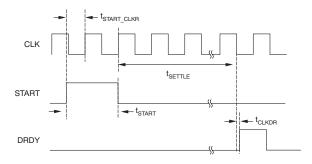


Figure 3. START Timing

TIMING REQUIREMENTS: START

At $T_A = -40^{\circ}$ C to +85°C, and DVDD = 2.7V to 3.3V.

SYMBOL	DESCRIPTION	MIN	ТҮР	MAX	UNIT
t _{START_CLKR}	Setup time, rising edge of START to rising edge of CLK	0.5			t _{CLK}
t _{start}	Start pulse width	1			t _{CLK}

ADS1672

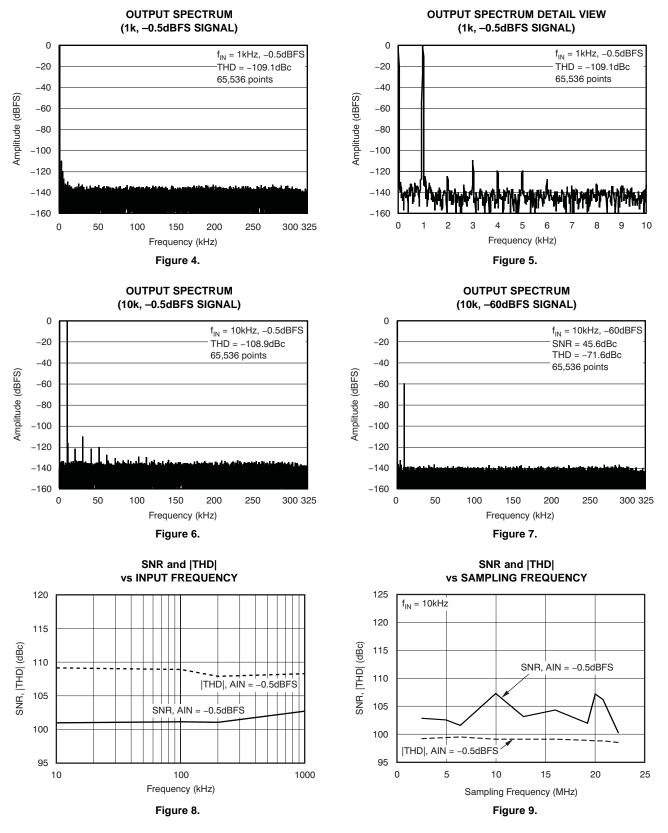


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TYPICAL CHARACTERISTICS

All specifications are at $T_A = -40^{\circ}$ C to +85°C, AVDD = 5V, DVDD = 3V, $f_{CLK} = 20$ MHz, $V_{REF} = +3V$, and $R_{BIAS} = 7.5$ k Ω , unless otherwise noted.



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TYPICAL CHARACTERISTICS (continued)

All specifications are at $T_A = -40^{\circ}$ C to +85°C, AVDD = 5V, DVDD = 3V, $f_{CLK} = 20$ MHz, $V_{REF} = +3V$, and $R_{BIAS} = 7.5$ k Ω , unless otherwise noted.

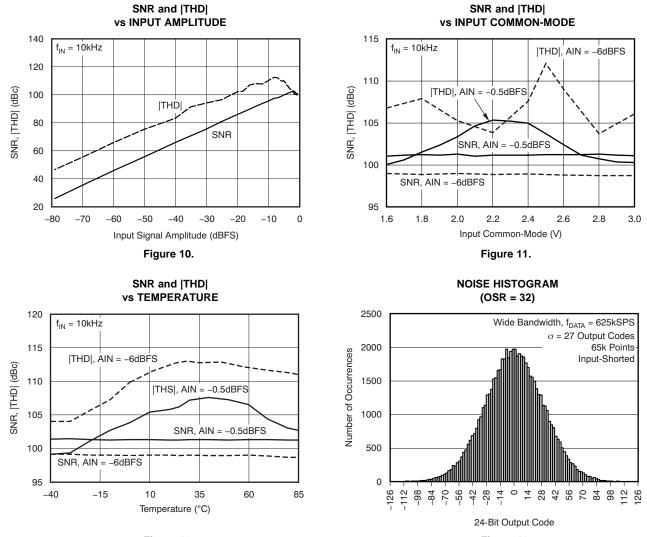


Figure 12.

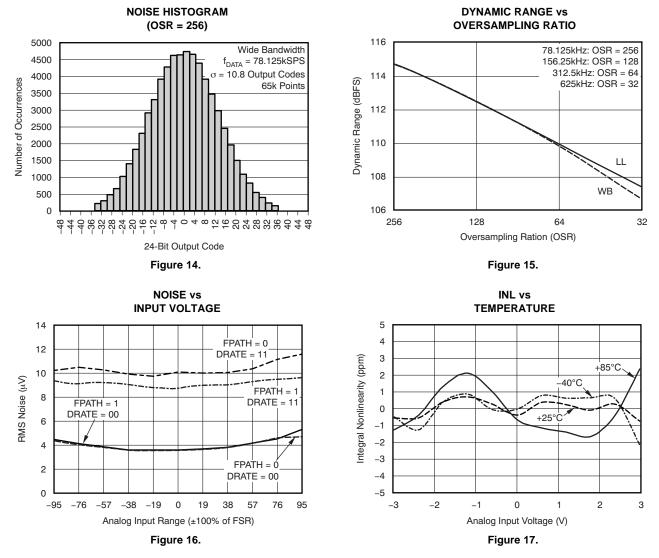
Figure 13.



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TYPICAL CHARACTERISTICS (continued)

All specifications are at $T_A = -40^{\circ}$ C to +85°C, AVDD = 5V, DVDD = 3V, $f_{CLK} = 20$ MHz, $V_{REF} = +3V$, and $R_{BIAS} = 7.5$ k Ω , unless otherwise noted.

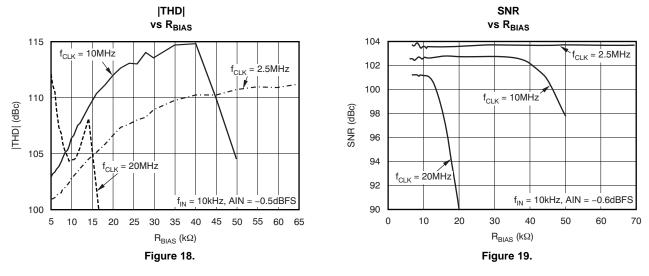


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TYPICAL CHARACTERISTICS (continued)

All specifications are at $T_A = -40^{\circ}$ C to +85°C, AVDD = 5V, DVDD = 3V, $f_{CLK} = 20$ MHz, $V_{REF} = +3V$, and $R_{BIAS} = 7.5$ k Ω , unless otherwise noted.



POWER vs R_{BIAS} 500 $f_{IN} = 10 \text{kHz}, \text{AIN} = -0.5 \text{dBFS}$ 450 400 350 Power (mW) 300 f_{CLK} = 20MHz 250 200 $f_{CLK} = 10MHz$ f_{CLK} = 2.5MHz 150 100 50 5 10 15 20 25 30 35 40 45 50 55 60 65 $R_{BIAS} (k\Omega)$ Figure 20.



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OVERVIEW

The ADS1672 is a 24-bit, $\Delta\Sigma$ analog-to-digital converter (ADC). It provides high-resolution measurements of both ac and dc signals and features an advanced multi-stage analog modulator with a programmable and flexible digital decimation filter.

Figure 21 shows a block diagram of the ADS1672. The modulator is chopper-stabilized for low-drift performance and measures the differential input signal $V_{IN} = (AINP - AINN)$ against the differential reference $V_{REF} = (VREFP - VREFN)$. The digital filter receives the modulator signal and processes it through the user-selected path. The low-latency path provides single-cycle settling, and is ideal when using a multiplexer or when measuring large transients. The wide-bandwidth path provides outstanding frequency response with very low passband ripple, a steep transition band, and large stop band attenuation. This path is well-suited for applications that require high-resolution measurements of high-frequency ac signal content.

A dedicated START pin allows precise conversion control; toggle the pin to begin the conversion process. The ADS1672 is configured by setting the appropriate I/O pins—there are no registers to program. Data are retrieved over a serial interface that can support either CMOS or LVDS voltage levels. In addition, the serial interface can be internally or externally clocked. This flexibility allows direct connection to a wide range of digital hosts including DSPs, FPGAs, and microcontrollers.

A detection circuit monitors the conversions to indicate when the inputs are out-of-range for an extended duration. A power-down pin (PDWN) shuts off all circuitry when the ADS1672 is not in use.

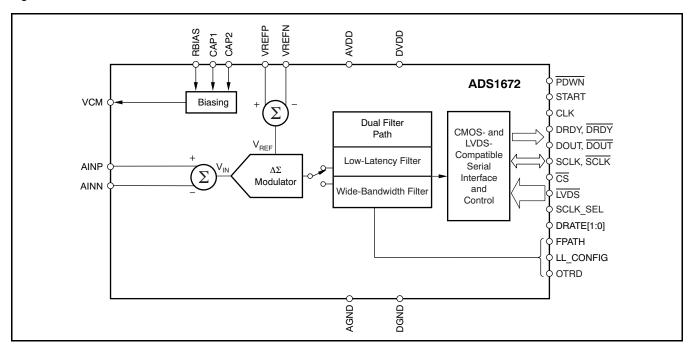


Figure 21. ADS1672 Block Diagram

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NOISE PERFORMANCE

The ADS1672 offers outstanding noise performance that can be optimized by adjusting the data rate. As the averaging is increased (thus reducing the data rate), the noise drops correspondingly. Table 2 shows the noise as a function of data rate for both the low-latency and the wide-bandwidth filter paths under the conditions shown.

Table 2 lists some of the more common methods of specifying noise. The dynamic range is the ratio of the root-mean-square (RMS) value of a full-scale sine wave to the RMS noise with the inputs shorted together. This value is expressed in decibels relative to full-scale (dBFS). The input-referred noise is the RMS value of the noise with the inputs shorted, referred to the input of the ADS1672. The effective number of bits (ENOB) is calculated from a dc perspective using the formula in Equation 1, where full-scale range equals $2V_{REF}$.

$$ENOB = \frac{In\left(\frac{Full-scale range}{RMS noise}\right)}{In(2)}$$

Noise-free bits specifies noise, again from a dc perspective using Equation 1, with peak-to-peak noise substituted for RMS noise.

ANALOG INPUTS (AINP, AINN)

The ADS1672 measures the differential signal, $V_{IN} = (AINP - AINN)$, against the differential reference, $V_{REF} = (VREFP - VREFN)$. The most positive measurable differential input is V_{REF} , which produces the most positive digital output code of 7FFFFh. Likewise, the most negative measurable differential input is $-V_{REF}$, which produces the most negative digital output code of 800000h.

Analog inputs must be driven with a differential signal to achieve optimum performance. The recommended common-mode voltage is 2.5V. The ADS1672 samples the analog inputs at very high speeds. It is critical that a suitable driver be used. See the *Application Information* section for recommended circuit designs.

The ADS1672 uses a switched-capacitor circuitry to measure the input voltage. Internal capacitors are charged by the inputs and then discharged internally with each clock (CLK) cycle. Figure 22 shows the effective input impedance seen by the driving amplifier.

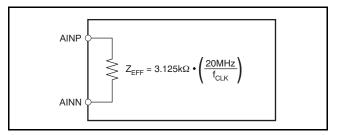


Figure 22. Effective Input Impedance

FILTER PATH	DATA RATE[1:0]	DATA RATE	DYNAMIC RANGE	INPUT-REFERRED NOISE	ENOB	NOISE-FREE BITS
	00	36kSPS	115dB	3.9μV _{RMS}	20.6	17.8
Low-Latency	01	68kSPS	113dB	5.0μV _{RMS}	20.2	17.5
(single-cycle settling configuration)	10	120kSPS	110dB	6.7μV _{RMS}	19.8	17.1
	11	180kSPS	108dB	8.9μV _{RMS}	19.4	16.7
	00	78.1kSPS	115.5dB	3.9μV _{RMS}	20.6	17.8
Wide-Bandwidth	01	156.3kSPS	113dB	5.0μV _{RMS}	20.2	17.5
	10	312.5kSPS	110dB	6.8μV _{RMS}	19.8	17.0
-	11	625.0kSPS	107dB	10.1μV _{RMS}	19.2	16.5

Table 2. Noise Performance⁽¹⁾

(1)

(1) $V_{REF} = 3V$, $f_{CLK} = 20MHz$.



VOLTAGE REFERENCE INPUTS (VREFN, VREFP)

The voltage reference for the ADS1672 is the differential voltage between VREFP and VREFN: $V_{REF} = (VREFP - VREFN)$ (2)

A high-quality reference voltage with the appropriate drive strength is essential for achieving the best performance from the ADS1672. Noise and drift on the reference degrade overall system performance. See the *Application Information* section for reference circuit examples.

It is recommended that a minimum 10μ F and 0.1μ F ceramic bypass capacitors be used directly across the reference inputs, VREFP and VREFN. These capacitors should be placed as close as possible to the device under test for optimal performance.

COMMON-MODE VOLTAGE (VCM)

The VCM pin outputs a voltage of AVDD/2 and can be used to set the common-mode output of the circuitry that drives the ADS1672. The pin must be bypassed with a 1μ F capacitor placed close to the package pin, even if it is not connected elsewhere. The VCM pin has very little drive capability and should not be used to drive any loads.

CONVERSION START

The START pin provides an easy and precise conversion control. To perform a single conversion, pulse the START pin as shown in Figure 23. The START signal is latched internally on the rising edge of CLK. Multiple conversions are performed by continuing to hold START high after the first conversion completes; see the digital filter descriptions for more details on multiple conversions, because the timing depends on the filter path selected.

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A conversion can be interrupted by issuing another START pulse before the ongoing conversion completes. When an interruption occurs, the data for the ongoing conversion are flushed and a new conversion begins. DRDY indicates that data are ready for retrieval after the filter has settled, as shown in Figure 24.

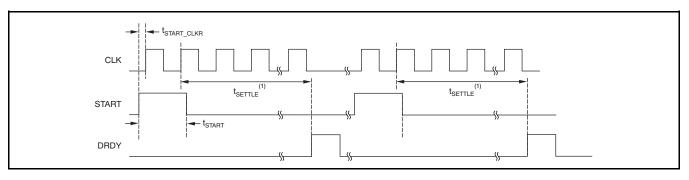
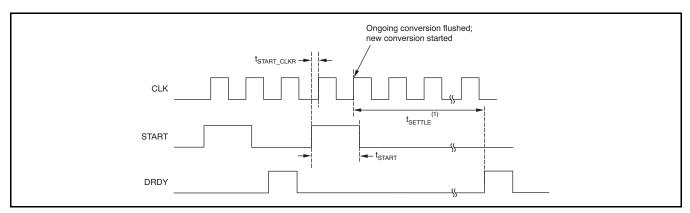


Figure 23. START Pin Used for Single Conversions



(1) See Low-Latency Filter section and Wide Bandwidth Filter section for specific values of settling time t_{SETTLE}.

Figure 24. Example of Restarting a Conversion with START

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DIGITAL FILTER

In delta-sigma ADCs, the digital filter has a critical influence on device performance. The digital filter sets the frequency response, data rate, bandwidth, and settling time. Choosing to optimize some of these features in a filter means that compromises must be made with other specifications. These tradeoffs determine the applications for which the device is best suited.

The ADS1672 offers two digital filters on-chip, and allows the user to direct the output data from the the Wide-Bandwidth or modulator to either Low-Latency filter. These filters allow the user to use one converter design to address multiple applications. The Low-Latency path filter has minimal latency or settling time. This path is ideal for measurements with large, quick changes on the inputs (for example, when using a multiplexer). The low-latency characteristic allows the user to cycle through the speeds. multiplexer at high The frequency characteristics are relaxed in order to provide the low latency.

The other path provides a filter with excellent frequency response characteristics. The passband ripple is extremely small, the transition band is very steep, and there is large stop band attenuation. These characteristics are needed for high-resolution measurements of ac signals. The tradeoff here is that settling time increases; but for signal processing, this increase is not generally a critical concern.

The FPATH digital input pin sets the filter path selection, as shown in Table 3. Note that the START pin must be strobed after a change to the filter path selection or data rate. If a conversion is in process during a filter path or data rate change, the output data are not valid and should be discarded.

Table 3.	ADS1672	Filter Path	Selection
----------	---------	-------------	-----------

FPATH PIN	SELECTED FILTER PATH
1	Low-latency path
0	Wide-bandwidth path

LOW-LATENCY DIGITAL FILTER

The low-latency (LL) filter provides a fast settling response targeted for applications that need high-precision measurements with minimal latency. A good example of this type of application is using a multiplexer to measure multiple inputs. The faster that the ADC settles, the faster the measurement can complete and the multiplexer can advance to the next input.

The ADS1672 LL filter supports two configurations to help optimize performance for these types of applications.

The LL_CONFIG input pin selects the configuration, as shown in Table 4. Be sure to strobe the START pin after changing the configuration. If a conversion is in process during a configuration change, the output data for that conversion are not valid and should be discarded.

Table 4. Low-Latency Pin Configurations

LL_CONFIG PIN	LOW-LATENCY CONFIGURATION
0	Single-cycle settling
1	Fast response

The first configuration is *single-cycle settling*. As the name implies, this configuration allows for the filter to completely settle in one conversion cycle; there is no need to discard data. Each data output is comprised of information taken during only the previous conversion. The DRATE[1:0] digital input pins select the data rate for the Single-Cycle Settling configuration, as shown in Table 5. Note that the START pin must be strobed after a change to the data rate change, the output data for that conversion are not valid and should be discarded.

DRATE[1:0]	DATA RATE (1/t _{DRDY-SCS})	SETTLING TI	ME, t _{SETTLE-LL}	–3dB BANDWIDTH ⁽¹⁾
00	36.30kSPS	27.55µs	550 t _{CLK}	34kHz
01	67.80kSPS	14.75μs	294 t _{CLK}	68kHZ
10	119.76kSPS	8.35µs	166 t _{CLK}	130kHZ
11	180.18kSPS	5.55µs	110 t _{CLK}	215kHz

 Table 5. Low-Latency Data Rates with Single-Cycle Settling Configuration

(1) The input signal aliases when its frequency exceeds $f_{DATA}/2$, in accordance with the Nyquist theorem.



The second configuration is *fast response*. The DRATE[1:0] digital input pins select the data rate for the Fast Response Configuration, as shown in Table 6. When selected, this configuration provides a higher output data rate. The faster output data rate allows for more averaging by a post-processor within a given time interval to reduce noise. It also provides a faster indication of changes on the inputs when monitoring quickly-changing signals (for example, in a control loop application).

Table 6. Low-Latency Data Rates withFast-Response Configuration

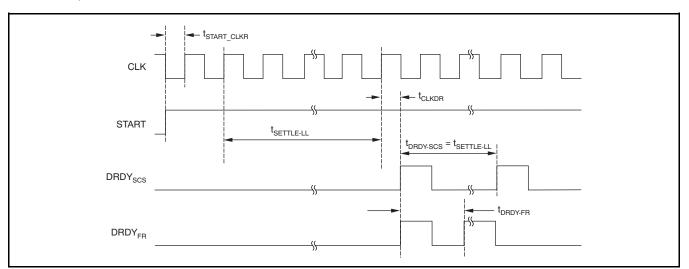
DRATE [1:0]	DATA RATE (1/t _{DRDY-FR})	SETTLIN t _{SETT}	IG TIME, IE-LL	–3dB BANDWIDTH
00	78.125kSPS	27.55µs	550 t _{CLK}	34kHz
01	156.25kSPS	14.75μs	294 t _{CLK}	68kHZ
10	312.5kSPS	8.35µs	166 t _{CLK}	130kHZ
11	625kSPS	5.55µs	110 t _{CLK}	215kHz

Settling Time

The settling time in absolute time (μ s) is the same for both configurations of the low-latency filter, as shown in Table 5 and Table 6. The difference between the configurations is seen with the timing of the conversions after the filter has settled from a pulse on the START pin. ADS1672

Figure 25 illustrates the response of both configurations on approximately the same time scale in order to highlight the differences. With the single-cycle settling configuration, each conversion fully settles; in other words, the conversion period $t_{DRDY-SCS} = t_{SETTLE-LL}$. The benefit of this configuration is its simplicity—the ADS1672 functions similar to a SAR converter and there is no need to consider discarding partially-settled data because each conversion is fully settled.

With the fast response configuration, the data rate for conversions after initial settling is faster; that is, the conversion time is less than the settling: $t_{DRDY-FR} < t_{SETTLE-U}$. One benefit of this configuration is a faster response to changes on the inputs, because data are supplied at a faster rate. Another advantage is better support for post-processing. For example, if multiple readings are averaged to reduce noise, the higher data rate of the fast response configuration allows this averaging to happen in less time than it requires with the single-cycle settling filter. A third benefit is the ability to measure higher input frequencies without aliasing as a result of the higher data rate.



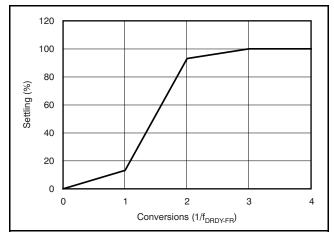
NOTE: DRDY_{SCS} is the DRDY output with the low-latency single-cycle settling configuration. DRDY_{FR} is the DRDY output with the low-latency fast-response settling configuration.

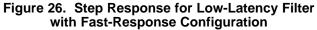
Figure 25. Low-Latency Single-Cycle Settling and Fast-Response Configuration Conversion Timing

SBAS402D – JUNE 2008 – REVISED JULY 2010

It is important to note, however, that the absolute settling time of the low-latency path does not change when using the fast response configuration. Changes on the input signal during conversions after the initial settling require multiple cycles to fully settle. To help illustrate this requirement, consider a change on the inputs as shown in Figure 29, where START is assumed to have been taken high before the input voltage was changed.

The readings after the input change settle as shown in Figure 26. Conversion 3 provides a fully-settled result at the new V_{IN} signal.





Frequency Response

Figure 27 shows the frequency response for the low-latency filter path normalized to the output data rate, f_{DATA} . The overall frequency response repeats at the modulator sampling rate, which is the same as the input clock frequency. Figure 28 shows the response with the fastest data rate selected (625kSPS when $f_{CLK} = 20$ MHz).

 0
 -10

 -20
 DRATE[1:0]='00'

 -20
 DRATE[1:0]='11'

 0
 -30

 -30
 DRATE[1:0]='11'

 -50
 -60

 -70
 -80

 0
 0.1
 0.2
 0.3
 0.4
 0.5
 0.6
 0.7
 0.8
 0.9
 1.0

 Frequency (f_{IN}/f_{DATA})
 FreqUPA (f_{IN}/f_{DATA})
 Frequency (f_{IN}/f_{DATA})</t

Figure 27. Frequency Response of Low-Latency Filter in Fast-Response Configuration

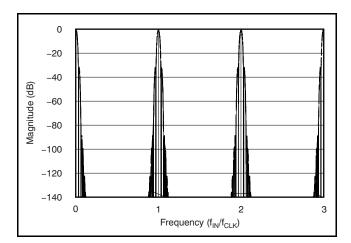
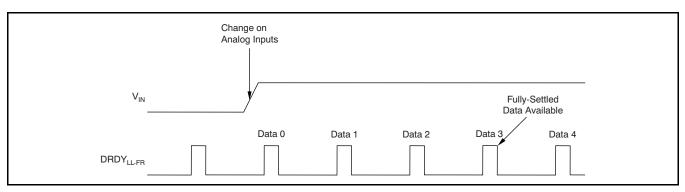


Figure 28. Extended Frequency Response of Low-Latency Path



NOTE: START pin held high previous to change on analog inputs.





Phase Response

The low-latency filter uses a multiple stage linear phase digital filter. Linear phase filters exhibit constant delay time versus input frequency (also know as *constant group delay*). This feature of linear phase filters means that the time delay from any instant of the input signal to the corresponding same instant of the output data is constant and independent of the input signal frequency. This behavior results in essentially zero phase error when measuring multi-tone signals.

WIDE-BANDWIDTH FILTER

The wide-bandwidth (WB) filter is well-suited for measuring high-frequency ac signals. This digital filter offers excellent passband and stop band characteristics.

The DRATE[1:0] digital input pins select from the four data rates available with the WB filter, as shown in Table 7. Note that the START pin must be strobed after a change to the data rate. If a conversion is in process during a data rate change, the output data for that conversion are not valid and should be discarded.

Table 7. Wide-Bandwidth Data Rates

DRATE [1:0]	DATA RATE (1/t _{DRDY-WB})	–3dB BANDWIDTH	SETTLING TIME, t _{SETTLE-WB}		
00	78.125kSPS	38kHz	704µs	14061 t _{CLK}	
01	156.25kSPS	76kHz	352µs	7033 t _{CLK}	
10	312.50kSPS	152kHz	176µs	3519 t _{CLK}	
11	625.0kSPS	305kHz	88µs	1762 t _{CLK}	

While using the wide-bandwidth filter path, the LL_CONFIG pin must be set to logic HIGH. Setting LL_CONFIG to a logic low forces the ADS1672 to switch to the low-latency filter path, single cycle settling mode overriding FPATH pin.

Frequency Response

Figure 30 shows the frequency response for the wide-bandwidth filter path normalized to the output data rate, f_{DATA} . Figure 31 shows the passband ripple, and the transition from passband to stop band is illustrated in Figure 32. These three plots are valid for all of the data rates available on the ADS1672. Simply substitute the selected data rate to express the x-axis in absolute frequency.

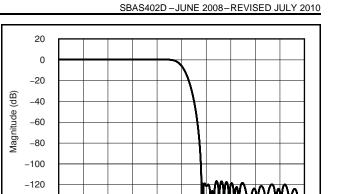


Figure 30. Frequency Response of Wide-Bandwidth Filter

0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 1.0

Frequency (f_{IN}/f_{DATA})

-140

0

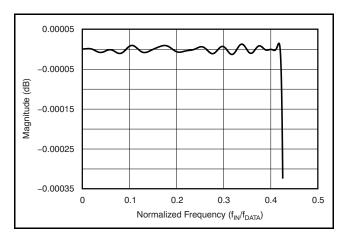


Figure 31. Passband Response for Wide-Bandwidth Filter

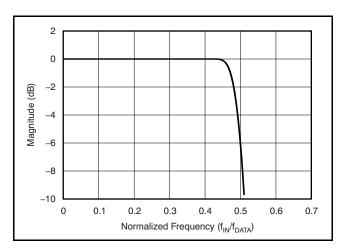


Figure 32. Transition Band Response for Wide-Bandwidth Filter



SBAS402D - JUNE 2008 - REVISED JULY 2010

The overall frequency response repeats at the modulator sampling rate, which is the same as the input clock frequency. Figure 33 shows the response with the fastest data rate selected (625kSPS when $f_{CLK} = 20MHz$).

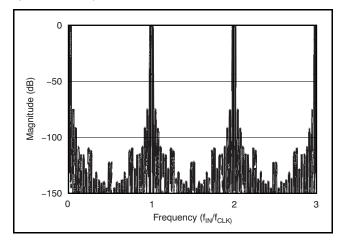


Figure 33. Extended Frequency Response of Wide-Bandwidth Path

Phase Response

The wide-bandwidth filter uses a multiple-stage, linear-phase digital filter. Linear phase filters exhibit constant delay time versus input frequency (also know as *constant group delay*). This feature means that the time delay from any instant of the input signal to the corresponding same instant of the output data is constant and independent of the input signal frequency. This behavior results in essentially zero phase error when measuring multi-tone signals.

Settling Time

The Wide-Bandwidth filter fully settles before indicating data are ready for retrieval after the START pin is taken high, as shown in Figure 35. For this filter, the settling time is larger than the conversion time: $t_{\text{SETTLE-WB}} > t_{\text{DRDY-WB}}$. Instantaneous steps on the input require multiple conversions to settle if START is not pulsed. Figure 34 shows the settling response with the x-axis normalized to conversions or data-ready cycles. The output is fully settled after 55 data-ready cycles.

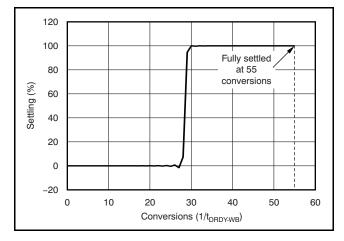
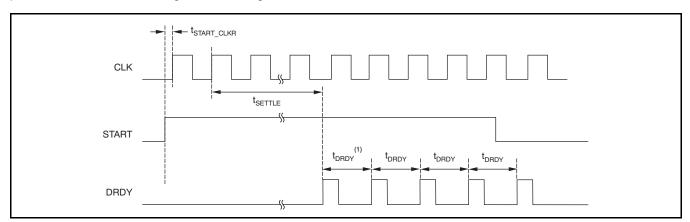


Figure 34. Step Response for Wide-Bandwidth Filter



(1) $t_{DRDY} = 1/f_{DATA}$. See Table 7 for the relationship between t_{SETTLE} and t_{DRDY} when using the Wide-Bandwidth filter.

Figure 35. START Pin Used for Multiple Conversions with Wide-Bandwidth Filter Path





OTRD FUNCTION

The ADS1672 provides an out-of-range (OTRD) pin that can be used in feedback loops to set the dynamic range of the input signal.

The OTRD function is triggered when the output code of the digital filter exceeds the positive or negative full-scale range. OTRD goes high on the rising edge of DRDY. When the digital output code returns within the full-scale range, OTRD returns low on the next rising edge of DRDY. OTRD can also be used when small out-of-range input glitches must be ignored.

SERIAL INTERFACE

The ADS1672 offers a flexible and easy-to-use, read-only serial interface designed to connect to a wide range of digital processors, including DSPs, microcontrollers, and FPGAs. The ADS1672 serial interface can be configured to support either standard CMOS voltage swings or low-voltage differential swings (LVDS). In addition, when using standard CMOS voltage swings, SCLK can be internally or externally generated.

The ADS1672 is entirely controlled by pins; there are no registers to program. Connect the I/O pins to the appropriate level to set the desired function. Whenever changing the I/O pins that are used to control the ADS1672, be sure to issue a START pulse immediately after the change in order to latch the new values.

USING LVDS OUTPUT SWINGS

When the LVDS pin is set to '0', the ADS1672 outputs are LVDS TIA/EIA-644A compliant. The data out, shift clock, and data ready signals are output on the differential pairs of pins DOUT/DOUT, SCLK/SCLK, and DRDY/DRDY, respectively. The voltage on the outputs is centered on 1.2V and swings approximately 350mV differentially. For more information on the LVDS interface, refer to the document *Low-Voltage Differential Signaling (LVDS) Design Notes* (literature number SLLA014) available for download at www.ti.com.

When using LVDS, the \overline{CS} function is not available and $\underline{SC}LK$ must be internally generated. The states of the \overline{CS} and $\underline{SC}LK_SEL$ pins are ignored, but do not leave these pins floating; they must be tied high or low.

USING CMOS OUTPUT SWINGS

When the LVDS pin is set to '1', the ADS1672 outputs are CMOS-compliant and swing from rail to rail. The data out and data ready signals are output on the differential pairs of pins DOUT/DOUT and DRDY/DRDY, respectively. Note that these are the same pins used to output LVDS signals when the LVDS pin is set to '0'. DOUT and DRDY are complementary outputs provided for convenience. When not in use, these pins should be left floating.

See the <u>Serial Shift Clock</u> section for a description of the SCLK and SCLK pins.

DATA OUTPUT (DOUT, DOUT)

Data are output serially from the ADS1672, MSB first, on the DOUT and DOUT pins. When LVDS signal swings are used, these two pins act as a differential pair to produce the LVDS-compatible differential output signal. When CMOS signal swings are used, the DOUT pin is the complement of DOUT. If DOUT is not used, it should be left floating.

DATA READY (DRDY, DRDY)

Data ready for retrieval are indicated on the DRDY and DRDY pins. When LVDS signal swings are used, these two pins act as a differential pair to produce the LVDS-compatible differential output signal. When CMOS signal swings are used, the DRDY pin is the complement of DRDY. If one of the data ready pins is not used when CMOS swings are selected, it should be left floating.

SERIAL SHIFT CLOCK (SCLK, SCLK, SCLK, SCLK)

The serial shift clock SCLK is used to shift out the conversion data, MSB first, onto the Data Output pins. Either an internally- or externally-generated shift clock can be selected using the SCLK_SEL pin. If SCLK_SEL is set to '0', a free-running shift clock is generated internally from the master clock and outputs on the SCLK and SCLK pins. The LVDS pin determines if the output voltages are CMOS or LVDS. If SCLK_SEL is set to '1' and LVDS is set to '1', the SCLK pin is configured as an input to accept an externally-generated shift clock. In this case, the SCLK pin always outputs low. When SCLK_SEL is set to '0', the SCLK and SCLK pins are configured as outputs, and the shift clock is generated internally using the master clock input (CLK).

When LVDS signal swings are used, the shift clock is automatically generated internally regardless of the state of SCLK_SEL. In this case, SCLK_SEL cannot be left floating; it must be tied high or low.

 Table 8 summarizes the ADS1672 supported serial clock configurations.

Table 8. Supported Serial Clock Configurations

DIGITAL OUTPUTS	SHIFT CLOCK (SCLK)
LVDS	Must be generated internally
CMOS	Internal (SCLK_SEL = '0')
CMOS	External (SCLK_SEL = '1')

CHIP SELECT (CS)

The chip select input (\overline{CS}) allows multiple devices to share a serial bus. When \overline{CS} is inactive (high), the serial interface is reset and the data output pins DOUT and \overline{DOUT} enter a high-impedance state. SCLK is internally generated; the SCLK and \overline{SCLK} output pins also enter a high-impedance state when \overline{CS} is inactive. The DRDY and \overline{DRDY} outputs are always active, regardless of the state of the \overline{CS} output. \overline{CS} may be permanently tied low when the outputs do not share a bus.

DATA FORMAT

The ADS1672 outputs 24 bits of data in two's complement format. A positive full-scale input produces an output code of 7FFFFFh, and the negative full-scale input produces an output code of 800000h. The output clips at these codes for signals

exceeding full-scale. Table 9 summarizes the ideal output codes for different input signals. When the input is positive out-of-range, exceeding the positive full-scale value of V_{REF} , the output clips to all 7FFFFFh. Likewise, when the input is negative out-of-range by going below the negative full-scale value of $-V_{REF}$, the output clips to 800000h.

Table 9. Ideal	Output	Code vs	Input	Signal
----------------	--------	---------	-------	--------

INPUT SIGNAL V _{IN} = (AINP – AINN)	IDEAL OUTPUT CODE ⁽¹⁾
≥ V _{REF}	7FFFFh
+V _{REF} 2 ²³ - 1	000001h
0	000000h
-V _{REF} 2 ²³ - 1	FFFFFh
$\leq -V_{\text{REF}}\left(\frac{2^{23}}{2^{23}-1}\right)$	8000000h

(1) Excludes effects of noise, INL, offset and gain errors.

CLOCK INPUT (CLK)

The ADS1672 requires that an external clock signal be applied to the CLK input pin. The sampling of the modulator is controlled by this clock signal. As with any high-speed data converter, a high-quality clock is essential for optimum performance. Crystal clock oscillators are the recommended CLK source; other sources, such as frequency synthesizers, are usually inadequate. Make sure to avoid excess ringing on the CLK input; keep the trace as short as possible.

Measuring high-frequency, large amplitude signals requires tight control of clock jitter. The uncertainty during sampling of the input from clock jitter limits the maximum achievable SNR. This effect becomes more pronounced with higher frequency and larger magnitude inputs. Fortunately, the ADS1672 oversampling topology reduces clock jitter sensitivity over that of Nyquist rate converters, such as pipeline and successive approximation converters, by at least a factor of $\sqrt{32}$.

For best performance, the duty cycle of CLK should be very close to 50%. The rise and fall times of the clock should be less than 2ns and the clock amplitude should be equal to AVDD.



SBAS402D - JUNE 2008-REVISED JULY 2010

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SYNCHRONIZING MULTIPLE ADS1672s

The START pin should be applied at power-up and resets the ADS1672 filters. START begins the conversion process, and the START pin enables simultaneous sampling with multiple ADS1672s in multichannel systems. All devices to be synchronized must use a common CLK input.

It is recommended that the START pin be aligned to the falling edge of CLK to ensure proper synchronization because the START signal is internally latched by the ADS1672 on the rising edge of CLK.

With the CLK inputs running, pulse START on the falling edge of CLK, as shown in Figure 36. Afterwards, the converters operate synchronously with the DRDY outputs updating simultaneously. After synchronization, DRDY is held high until the digital filter has fully settled.

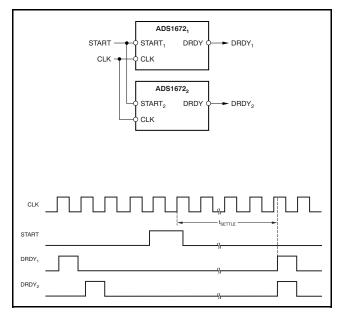
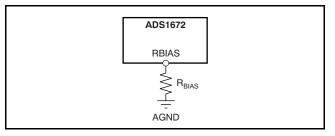
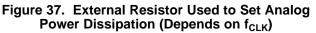


Figure 36. Synchronizing Multiple Converters

ANALOG POWER DISSIPATION

An external resistor connected between the RBIAS pin and the analog ground sets the analog current level, as shown in Figure 37. The current is inversely proportional to the resistor value. Figure 18 and Figure 20 (in the Typical Characteristics) show power and typical performance at values of R_{BIAS} for different CLK frequencies. Notice that the analog current can be reduced when using a slower frequency CLK input because the modulator has more time to settle. Avoid adding any capacitance in parallel to R_{BIAS} , because this additional capacitance interferes with the internal circuitry used to set the biasing.





POWER DOWN (PDWN)

When not in <u>use, the</u> ADS1672 can be powered down by taking the PDWN pin low. All circuitry shuts down, including the voltage reference. To minimize the digital current during power down, stop the clock signal supplied to the CLK input. Make sure to allow time for the reference to start up after exiting power-down mode.

After the reference has stabilized, allow for the modulator and digital filter to settle before retrieving data.

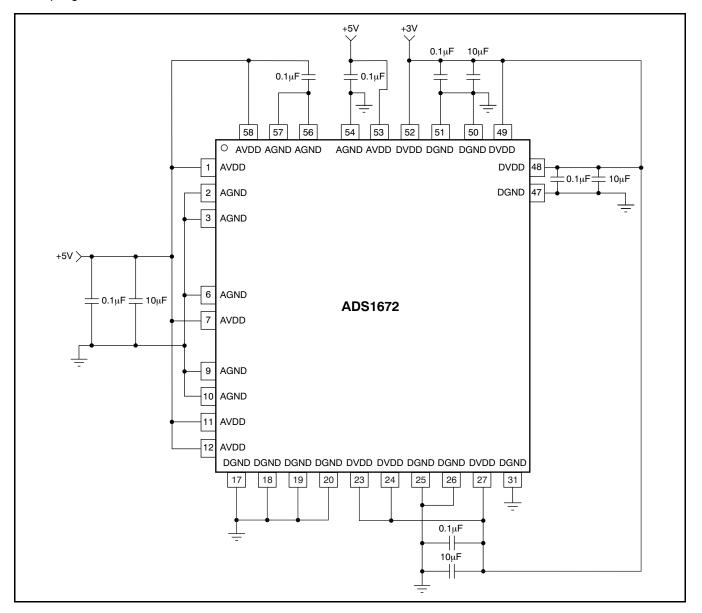


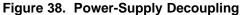
SBAS402D -JUNE 2008-REVISED JULY 2010

POWER SUPPLIES

Two supplies are used on the ADS1672: analog (AVDD) and digital (DVDD). Each supply must be suitably bypassed to achieve the best performance. It is recommended that a 1μ F and 0.1μ F ceramic capacitor be placed as close to each supply pin as possible. Connect each supply-pin bypass capacitor to the associated ground. Each main supply bus should also be bypassed with a bank of capacitors from 47μ F to 0.1μ F. Figure 38 illustrates the recommended method for ADS1672 power-supply decoupling.

Power-supply pins 53 and 54 are used to drive internal clock supply circuits and, as a result, are generally very noisy. It is highly recommended that traces from these pins not be shared or run close to any of the adjacent AVDD or AGND pins of the ADS1672. These pins should be well-decoupled, using a 0.1μ F ceramic capacitor placed close to the pins, and immediately terminated into the power and ground planes.







SBAS402D - JUNE 2008 - REVISED JULY 2010

APPLICATIONS INFORMATION

To obtain the specified performance from the ADS1672, the following layout and component guidelines should be considered.

- 1. **Power Supplies:** The device requires two power supplies for operation: DVDD and AVDD. For both supplies, use a 10μ F tantalum capacitor, bypassed with a 0.1μ F ceramic capacitor, placed close to the device pins. Alternatively, a single 10μ F ceramic capacitor can be used. The supplies should be relatively free of noise and should not be shared with devices that produce voltage spikes (such as relays, LED display drivers, etc.). If a switching power supply source is used, the voltage ripple should be low (< 2mV). The power supplies may be sequenced in any order.
- 2. **Ground Plane:** A single ground plane connecting both AGND and DGND pins can be used. If separate digital and analog grounds are used, connect the grounds together at the converter.
- 3. **Digital Inputs:** Source terminate the digital inputs to the device with 50Ω series resistors. The resistors should be placed close to the driving end of the digital source (oscillator, logic gates, DSP, etc.) These resistors help reduce ringing on the digital lines, which may lead to degraded ADC performance.
- 4. Analog/Digital Circuits: Place analog circuitry (input buffer, reference) and associated tracks together, keeping them away from digital circuitry (DSP, microcontroller, logic). Avoid crossing digital tracks across analog tracks to reduce noise coupling and crosstalk.
- 5. **Reference Inputs:** Use a minimum 10μ F tantalum with a 0.1μ F ceramic capacitor directly across the reference inputs, VREFP and VREFN. The reference input should be driven by a low-impedance source. For best performance, the reference should have less than 3μ V_{RMS} broadband noise. For references with higher noise, external reference filtering may be necessary. The ADS1672 has 800Ω of resistance

across the VREFP and VREFN pins. The driving amplifier must be able to provide this current as well as another 1mA caused by switching at 20MHz. It is therefore recommended that the driving amplifier be able to provide at least 5mA, and enough decoupling capacitors be installed to attenuate instantaneous current spikes seen at 20MHz.

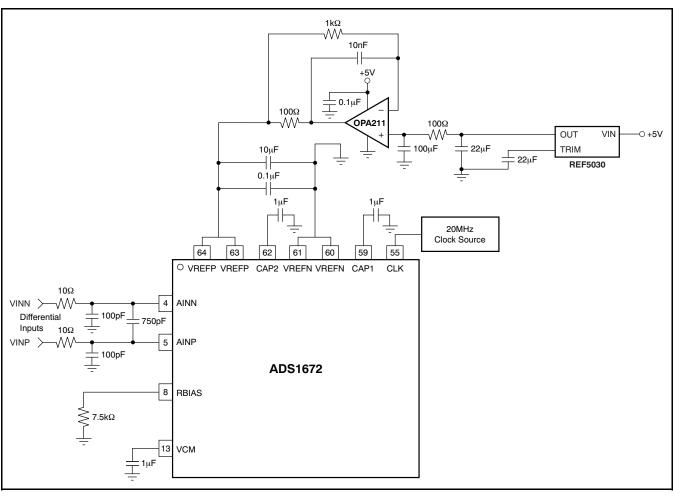
- 6. Analog Inputs: The analog input pins must be driven differentially to achieve specified performance. A true differential driver or transformer (ac applications) can be used for this purpose. Route the analog inputs tracks (AINP, AINN) as a pair from the buffer to the converter using short, direct tracks and away from digital tracks. A 750pF capacitor should be used directly across the analog input pins, AINP and AINN. A low-k dielectric (such as COG or film type) should be used to maintain low THD. Capacitors from each analog input to ground should be used. They should be no larger than 1/10 the size of the difference capacitor (typically 100pF) to preserve the ac common-mode performance.
- 7. **Component Placement:** Place the power supply, analog input, and reference input bypass capacitors as close as possible to the device pins. This placement is particularly important for the small-value ceramic capacitors. Surface-mount components are recommended to avoid the higher inductance of leaded components.

Figure 39 to Figure 41 illustrate basic connections and interfaces that can be used with the ADS1672. The THS4520 and THS4503 are good input drivers for the ADS1672. The THS4520 is a single-supply, high-speed, low-power, fully differential amplifier. The THS4503 is a high-speed, bipolar, fully differential amplifier. The wider supply range of the THS4503 provides better THD and SFDR performance over the entire input range of the converter, while sacrificing noise. The THS4520 offers comparable performance with lower power and higher noise performance.

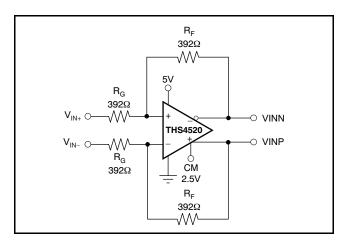


SBAS402D -JUNE 2008-REVISED JULY 2010

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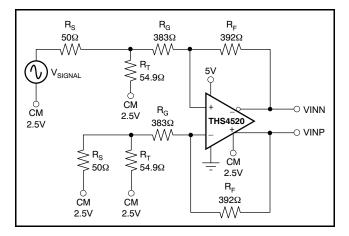


Figure 41. Basic Single-Ended Input Signal Interface

SBAS402D-JUNE 2008-REVISED JULY 2010

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REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Ch	anges from Revision C (June, 2009) to Revision D Page	е
•	Changed THD performance from –115dB to –113dB in <i>Features</i> list 1	1
•	Revised Description text to reflect 86dB stop band attenuation 1	1
•	Updated total harmonic distortion parameter typical specification for f _{IN} = 10kHz, -6dBFS to -113dB from -118dB	3
•	Changed stop band attenuation typical specification from 115dB to 86dB	3
•	Revised Figure 1 to show correct SCLK and DRDY timing sequence	7
•	Revised description ot t _{DRSCLK} timing	7
•	Deleted previously numbered Figures 6, 7, and 9	
•	Revised Figure 8	9
•	Updated Figure 9	9
•	Changed Figure 10 to more closely represent actual device performance 10	0
•	Revised Figure 12 10	0
•	Added paragraph about switched-capacitor circuitry and Figure 22 to Analog Inputs (AINP, AINN) section	4
•	Revised Reference Inputs discussion; added statements about requirements of driving amplifier	5

Changes from Revision B (November, 2008) to Revision C

•	Added test condition to Integral nonlinearity parameter	3
•	Deleted typical specification for Offset error parameter	3
•	Revised last sentence of Common-Mode Voltage (VCM) section.	15
•	Updated Figure 36	23

Page



PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
ADS1672IPAG	Active	Production	TQFP (PAG) 64	160 JEDEC TRAY (5+1)	Yes	NIPDAU	Level-4-260C-72 HR	-40 to 85	ADS1672I
ADS1672IPAG.A	Active	Production	TQFP (PAG) 64	160 JEDEC TRAY (5+1)	Yes	NIPDAU	Level-4-260C-72 HR	-40 to 85	ADS1672I
ADS1672IPAGG4	Active	Production	TQFP (PAG) 64	160 JEDEC TRAY (5+1)	Yes	NIPDAU	Level-4-260C-72 HR	-40 to 85	ADS1672I
ADS1672IPAGG4.A	Active	Production	TQFP (PAG) 64	160 JEDEC TRAY (5+1)	Yes	NIPDAU	Level-4-260C-72 HR	-40 to 85	ADS1672I
ADS1672IPAGR	Active	Production	TQFP (PAG) 64	1500 LARGE T&R	Yes	NIPDAU	Level-4-260C-72 HR	-40 to 85	ADS1672I
ADS1672IPAGR.A	Active	Production	TQFP (PAG) 64	1500 LARGE T&R	Yes	NIPDAU	Level-4-260C-72 HR	-40 to 85	ADS1672I

⁽¹⁾ **Status:** For more details on status, see our product life cycle.

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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PACKAGE OPTION ADDENDUM

14-Jul-2025

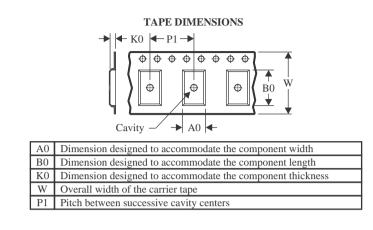
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All	dimensions are	e nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADS1672IPAGR	TQFP	PAG	64	1500	330.0	24.4	13.0	13.0	1.5	16.0	24.0	Q2



PACKAGE MATERIALS INFORMATION

15-Jul-2025



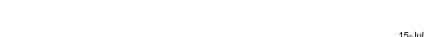
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ADS1672IPAGR	TQFP	PAG	64	1500	350.0	350.0	43.0

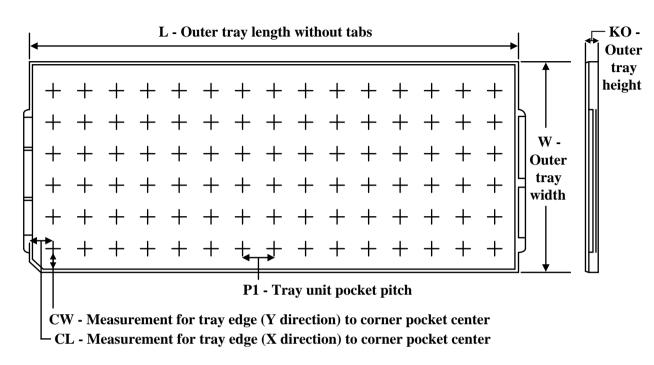
Texas Instruments

www.ti.com

TRAY



PACKAGE MATERIALS INFORMATION



Chamfer on Tray corner indicates Pin 1 orientation of packed units.

Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
ADS1672IPAG	PAG	TQFP	64	160	8 x 20	150	315	135.9	7620	15.2	13.1	13
ADS1672IPAG.A	PAG	TQFP	64	160	8 x 20	150	315	135.9	7620	15.2	13.1	13
ADS1672IPAGG4	PAG	TQFP	64	160	8 x 20	150	315	135.9	7620	15.2	13.1	13
ADS1672IPAGG4.A	PAG	TQFP	64	160	8 x 20	150	315	135.9	7620	15.2	13.1	13

*All dimensions are nominal

15-Jul-2025

MECHANICAL DATA

MTQF006A - JANUARY 1995 - REVISED DECEMBER 1996

PAG (S-PQFP-G64)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-026



LAND PATTERN DATA



A. All linear dimensions are in millimeters.B. This drawing is subject to change without no

- B. This drawing is subject to change without notice.
 C. Laser cutting apertures with trapezoidal walls and also rounding corner
 - C. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
 - D. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



LAND PATTERN DATA



A. All linear dimensions are in millimeters.B. This drawing is subject to change without no

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 - D. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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